





<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  (PTO-1449)				ATTY. DOCKET NO. 5920/FET/DV		SERIAL NO. 09/943,383	
				APPLICANT SHANMUGASUNDRAM et al.			
				FILING DATE August 31, 2001		GROUP	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	4,796,194	01/03/89	Atherton			08/20/86	
	5,089,970	02/18/92	Lee et al.			10/05/89	
	5,108,570	04/28/92	Wang			03/30/90	
	5,220,517	06/15/93	Sierk et al.			08/31/90	
	5,236,868	08/17/93	Nulman			04/20/90	
	5,260,868	11/09/93	Gupta et al.			10/15/91	
	5,295,242	03/15/94	Mashruwala et al.			11/02/90	
	5,309,221	05/03/94	Fischer et al.			12/31/91	
	5,329,463	07/12/94	Sierk et al.			01/13/93	
	5,367,624	11/22/94	Cooper			06/11/93	
	5,398,336	03/14/95	Tantry et al.			06/16/93	
	5,402,367	03/28/95	Sullivan et al.			07/19/93	
	5,408,405	04/18/95	Mozumder et al.			09/20/93	
	5,410,473	04/25/95	Kaneko et al.			12/16/92	
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	01-283934	11/15/89	Japan			X	
	2,050,247	08/29/91	Canada			X	
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
Dishon, G., D. Eylon, M. Finarov, and A. Shulman. "Dielectric CMP Advanced Process Control Based on Integrated Monitoring." Ltd. Rehoveth, Israel: Nova Measuring Instruments.							
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						Yes	No
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	Rampalli, Prasad, Arakere Ramesh, and Nimish Shah. 1991. <i>CEPT—A Computer-Aided Manufacturing Application for Managing Equipment Reliability and Availability in the Semiconductor Industry</i> . New York, New York: IEEE.

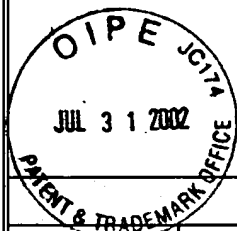
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	5,910,011	06/08/99	Cruse			05/12/97
	6,054,379	04/25/00	Yau et al.			02/11/98



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	05-151231	06/18/93	Japan				X
	05-216896	08/27/93	Japan				X
	05-266029	10/15/93	Japan				X
	06-110894	04/22/94	Japan				X
	06-176994	06/24/94	Japan				X
	06-252236	09/09/94	Japan				X
	06-260380	09/16/94	Japan				X
	08-149583	06/07/96	Japan			X	
	09-34535	02/07/97	Japan			X	
	EP 0877308 A2	11/11/98	Europe			X	
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		1072967A3	11/21/01	Europe			X

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<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
D	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
D	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
D	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
D	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
D	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	Translation  Yes No	
/	/					/	/
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
D	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.						
D	Telfeyan, Roland, James Moyne, Nauman Chaudhry, James Pugmire, Scott Shellman, Duane Boning, William Moyne, Arnon Hurwitz, and John Taylor. October 1995. "A Multi-Level Approach to the Control of a Chemical-Mechanical Planarization Process." Minneapolis, Minnesota: 42 <sup>nd</sup> National Symposium of the American Vacuum Society.						
D	Chang, E., B. Stine, T. Maung, R. Divecha, D. Boning, J. Chung, K. Chang, G. Ray, D. Bradbury, O. S. Nakagawa, S. Oh, and D. Bartelink. December 1995. "Using a Statistical Metrology Framework to Identify Systematic and Random Sources of Die- and Wafer-level ILD Thickness Variation in CMP Processes." Washington, D.C.: International Electron Devices Meeting.						
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EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide		
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow		
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes		
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions		

## FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	Translation	
						Yes	No

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	Dishon, G., M. Finarov, R. Kipper, J.W. Curry, T. Schraub, D. Trojan, 4 <sup>th</sup> Stambaugh, Y. Li and J. Ben-Jacob. February 1996. "On-Line Integrated Metrology for CMP Processing." Santa Clara, California: VMIC Speciality Conferences, 1 <sup>st</sup> International CMP Planarization Conference.
	Smith, Taber, Duane Boning, James Moyne, Arnon Hurwitz, and John Curry. June 1996. "Compensating for CMP Pad Wear Using Run by Run Feedback Control." Santa Clara, California: VLSI Multilevel Interconnect Conference.
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	SEMI. [1986] 1996. "Standard for Definition and Measurement of Equipment Reliability, Availability, and Maintainability (RAM)." SEMI E10-96.

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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT APPLICATION NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium		

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	Translation
						Yes No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Van Zant, Peter. 1997. <i>Microchip Fabrication: A Practical Guide to Semiconductor Processing</i> . Third Edition, pp. 472-478. New York, New York: McGraw-Hill.
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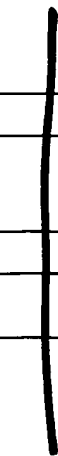

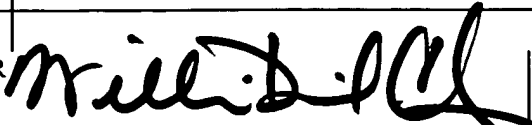
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				APPLICANT SHANMUGASUNDRAM et al.			
				FILING DATE August 31, 2001		GROUP	



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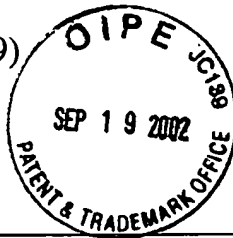
FOREIGN PATENT DOCUMENTS						
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						Yes No

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	Moyne, James. October 1999. "Advancements in CMP Process Automation and Control." Hawaii: (Invited paper and presentation to) Third International Symposium on Chemical Mechanical Polishing in IC Device Manufacturing: 196 <sup>th</sup> Meeting of the Electrochemical Society.  Consilium. November 1999. <i>FAB300™ Update</i> .  SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. SEMI E105-1000.  Lee, Brian, Duane S. Boning, Winthrop Baylies, Noel Poduje, Pat Hester, Yong Xia, John Valley, Chris Koliopoulus, Dale Hetherington, HongJiang Sun, and Michael Lacy. April 2001. "Wafer Nanotopography Effects on CMP: Experimental Validation of Modeling Methods." San Francisco, California: Materials Research Society Spring Meeting.
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	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,208,765	05/04/93	Turnbull			07/20/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
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	5,469,361	11/21/95	Moyne			06/06/94
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	5,603,707	02/18/97	Trombetta et al.			11/28/95
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	61-171147	08/01/86	Japan				X
	6-184434	07/05/94	Japan				X
	0 621 522 A2	10/26/94	Europe			X	
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	October 1984. "Method to Characterize the Stability of a Step and Repeat Lithographic System." <i>IBM Technical Disclosure Bulletin</i> , pp. 2857-2860.

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*Michael J. [Signature]*

DATE CONSIDERED

*12/9/03*

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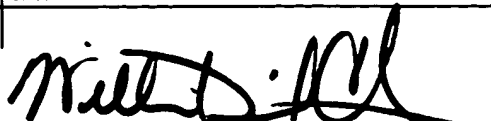
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	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
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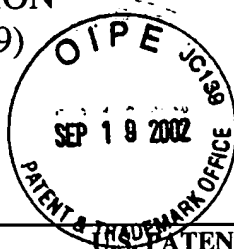
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	10-173029	06/26/98	Japan				X
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	Baliga, John. July 1999. "Advanced Process Control: Soon to be a Must." Cahners Semiconductor International. <a href="http://www.semiconductor.net/semiconductor/issues/issues/1999/jul99/docs/feature1.asp">www.semiconductor.net/semiconductor/issues/issues/1999/jul99/docs/feature1.asp</a>
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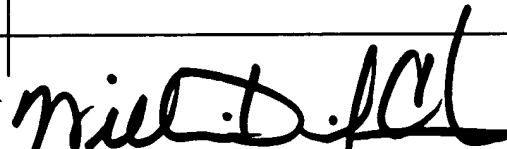
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				APPLICANT SHANMUGASUNDRAM et al.			
				FILING DATE August 31, 2001		GROUP	
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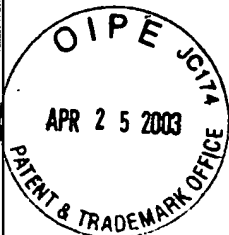
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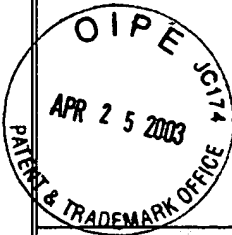
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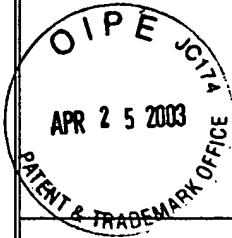
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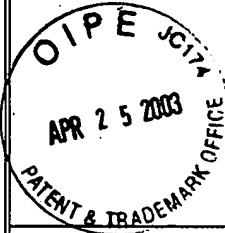
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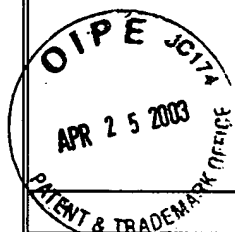
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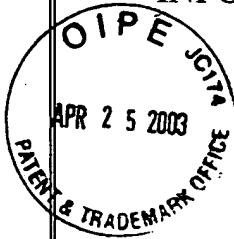
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